

SEMICONDUCTOR PACKAGE AND METHOD FOR FABRICATING THE SAME

ABSTRACT

A semiconductor package and a method for fabricating the same are proposed, wherein, in a molding process for encapsulating a semiconductor chip mounted on a substrate, a mold is used with a molding cavity formed with a plurality of recess portions relatively smaller in height, and with a plurality of air vents for connecting the recess portions to outside of the mold and for ventilate air in the molding cavity. This allows a molding resin used during molding to slow down its flow when flowing into the recess portions, as the molding resin rapidly absorbs heat transmitted from the mold and is increased in viscosity thereof. The slowed down molding resin can therefore be prevented from flashing out of the air vents, so that quality and appearance of the fabricated semiconductor package can be well assured.

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